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Part Number: 0736440213

Status: Active

Overview: HDM Backplane Connector System

Description: HDM Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location

A, Polarizing Key Position G, 72 Circuits, Mating Length 6.00mm

Documents:

3D Model Packaging Specification PK-70873-0818 (PDF)

<u>Drawing (PDF)</u> <u>RoHS Certificate of Compliance (PDF)</u>

Agency Certification

CSA LR19980 UL E29179

General

Product Family Backplane Connectors

Series 73644
Application Backplane

Comments Standard Press-Fit, Standard Press-Fit

Component Type PCB Header

Overview HDM Backplane Connector System

Product Name HDM

UPC 800753260641

Physical

Circuits (Loaded) 72
Circuits (maximum) 72

Color - Resin Black, Natural

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Yes

Material - Metal Phosphor Bronze, Stainless Steel

Material - Plating Mating Gold Material - Plating Termination Gold

Material - Resin High Temperature Thermoplastic

Number of Columns 12

Number of Pairs Open Pin Field

Number of Rows 6 Orientation Vertical PC Tail Length 3.50mm **PCB** Locator Nο **PCB** Retention Yes PCB Thickness - Recommended 2.50mm Packaging Type Tube Pitch - Mating Interface 2.00mm Pitch - Termination Interface 2.00mm 0.762µm

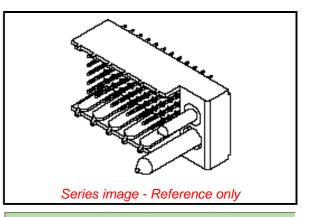
Plating min - Mating
Plating min - Termination
Polarized to PCB
Stackable
Surface Mount Compatible (SMC)

2.00film
0.762µm
0.051µm
No
Yes

Temperature Range - Operating -55° to +105°C

Termination Interface: Style Through Hole - Compliant Pin

Electrical



EU ELV

Not Reviewed

EU RoHS China RoHS

Not Reviewed REACH SVHC Not Reviewed Halogen-Free Status

Not Reviewed

For more information, please visit Contact US

China ROHS Not Reviewed ELV Not Reviewed RoHS Phthalates Not Reviewed

Search Parts in this Series

73644 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

DescriptionProduct #Extraction Tool621001000Backplane Insertion621001400

Signal Contact Tool

Backplane Signal 622008502

Insertion Module
Press-In Tool for
2.00mm Pitch HDM*
Board-to-Board
Backplane Header

Current - Maximum per Contact 1.0A 1.0 Gbps Data Rate Real Signals (per 25mm) 75 Shielded No Voltage - Maximum 250V AC

Material Info

Reference - Drawing Numbers Packaging Specification PK-70873-0818 Sales Drawing SDA-73644-XXXX

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